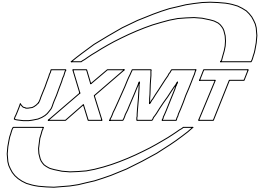
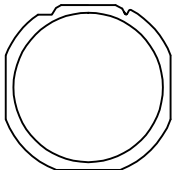
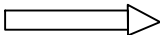
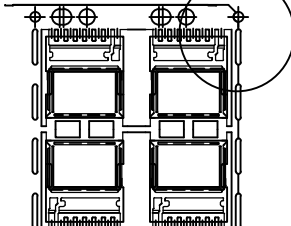
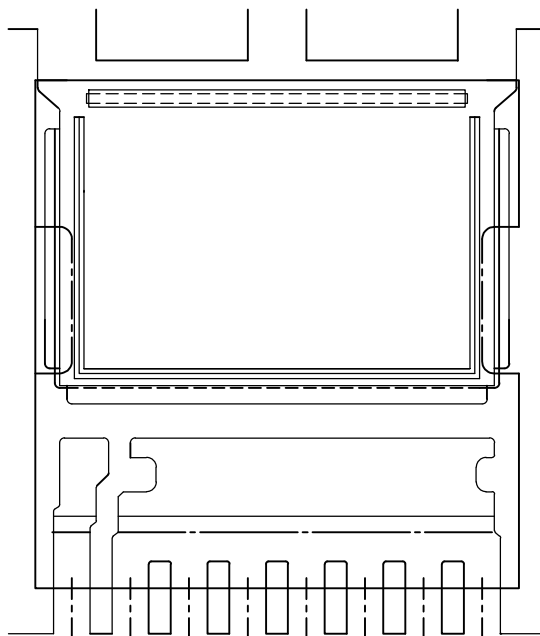


# Bonding Diagram

	安徽积芯微电子科技有限公司 Anhui Jixin Microelectronics Technology Ltd.					
	BD No.				版本	
	Device		Package	TOLLA-JX	Customer	
装片方向 	引线框传输方向 				客户确认  	



BOM	TYPE					
	Die Name	Wafer Size (inch)	Die Size Without SL(um)	Gate Pad Size (um)	Scribe Line (um)	Die Thickness (um)
芯片CHIP						
引线框物料号 L/F Material No:		栅极线材规格 Gate Wire Spec.		银胶 Epoxy		晶圆背金 Wafer back material
基岛尺寸 (mm) L/F Pad Size	7.9 * 5.35	源极线材规格 Source Wire Spec.		锡丝 Soft solder		
电镀方式 L/F Plating Type		总线数 Total Qt'y		塑封料 Compound		晶圆正面金属 Wafer top material
焊线方式 Wire Type		产品等级 MSL Level		电镀方式 Plating Type		
线图来源 BD source			备注 Remark			
制图日期			有效期	<input type="checkbox"/> 永久 <input type="checkbox"/> 六个月 <input type="checkbox"/> 其他		
拟制 Prepared By		审核 Checked By		批准 Approved By		文控发行章 Controlled Chapter